

# MC10H124

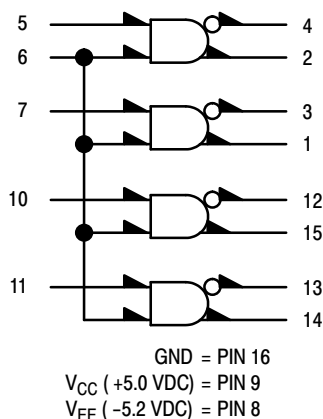
## Quad TTL-to-MECL Translator With TTL Strobe Input

### Description

The MC10H124 is a quad translator for interfacing data and control signals between a saturated logic section and the MECL section of digital systems. The 10H part is a functional/pinout duplication of the standard MECL 10K™ family part, with 100% improvement in propagation delay, and no increase in power-supply current.

### Features

- Propagation Delay, 1.5 ns Typical
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K Compatible
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

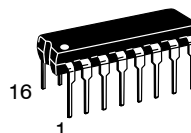


**Figure 1. Logic Diagram**



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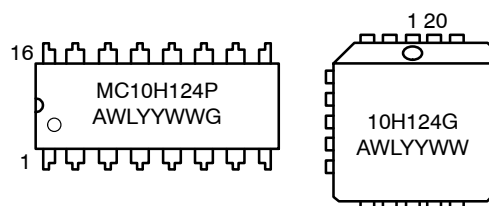


**PDIP-16**  
**P SUFFIX**  
**CASE 648-08**



**PLCC-20**  
**FN SUFFIX**  
**CASE 775-02**

### MARKING DIAGRAMS\*



A = Assembly Location  
 WL, L = Wafer Lot  
 YY, Y = Year  
 WW, W = Work Week  
 G or ■ = Pb-Free Package

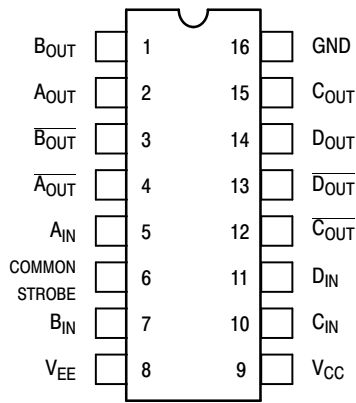
\*For additional marking information, refer to Application Note [AND8002/D](#).

### ORDERING INFORMATION

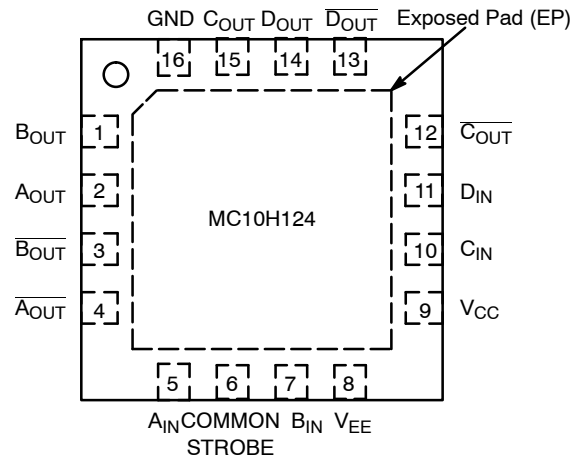
Device	Package	Shipping†
MC10H124FNG	PLCC-20 (Pb-Free)	46 Units/Tube
MC10H124FNR2G	PLCC-20 (Pb-Free)	500/Tape & Reel
MC10H124PG	PDIP-16 (Pb-Free)	25 Units/Tube

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

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Pin assignment is for Dual-in-Line Package.  
For PLCC pin assignment, see Table 1.



Pin assignment for QFN16 Package.

**Figure 2. Pin Assignment**

**Table 1. DIP CONVERSION TABLE**  
**16-Pin DIL to 20-Pin PLCC**

16 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
20 PIN PLCC	2	3	4	5	7	8	9	10	12	13	14	15	17	18	19	20

**Table 2. MAXIMUM RATINGS**

Symbol	Characteristic	Rating	Unit
$V_{EE}$	Power Supply ( $V_{CC} = 5.0$ V)	-8.0 to 0	Vdc
$V_{CC}$	Power Supply ( $V_{EE} = -5.2$ V)	0 to +7.0	Vdc
$V_I$	Input Voltage ( $V_{CC} = 5.0$ V) TTL	0 to $V_{CC}$	Vdc
$I_{out}$	Output Current Continuous Surge	50 100	mA
$T_A$	Operating Temperature Range	0 to +75	°C
$T_{stg}$	Storage Temperature Range Plastic Ceramic	-55 to +150 -55 to +165	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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**Table 3. ELECTRICAL CHARACTERISTICS** ( $V_{EE} = -5.2 \text{ V} \pm 5\%$ ,  $V_{CC} = 5.0 \text{ V} \pm 5.0\%$ )

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
$I_E$	Negative Power Supply Drain Current	–	72	–	66	–	72	mA
$I_{CCH}$ $I_{CCL}$	Positive Power Supply Drain Current	– –	16 25	– –	16 25	– –	18 25	mA
$I_R$	Reverse Current Pin 6 Pin 7	– –	200 50	– –	200 50	– –	200 50	μA
$I_F$	Forward Current Pin 6 Pin 7	– –	–12.8 –3.2	– –	–12.8 –3.2	– –	–12.8 –3.2	mA
$V_{(BR)in}$	Input Breakdown Voltage	5.5	–	5.5	–	5.5	–	Vdc
$V_I$	Input Clamp Voltage	–	–1.5	–	–1.5	–	–1.5	Vdc
$V_{OH}$	High Output Voltage	–1.02	–0.84	–0.98	–0.81	–0.92	–0.735	Vdc
$V_{OL}$	Low Output Voltage	–1.95	–1.63	–1.95	–1.63	–1.95	–1.60	Vdc
$V_{IH}$	High Input Voltage	2.0	–	2.0	–	2.0	–	Vdc
$V_{IL}$	Low Input Voltage	–	0.8	–	0.8	–	0.8	Vdc

1. Each MECL 10H™ series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfp/m is maintained. Outputs are terminated through a 50 Ω resistor to –2.0 V.

**Table 4. AC CHARACTERISTICS**

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
$t_{pd}$	Propagation Delay	0.55	2.5	0.55	2.65	0.85	3.1	ns
$t_r$	Rise Time	0.5	1.5	0.5	1.6	0.5	1.7	ns
$t_f$	Fall Time	0.5	1.5	0.5	1.6	0.5	1.7	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfp/m. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

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## APPLICATIONS INFORMATION

The MC10H124 has TTL-compatible inputs and MECL complementary open-emitter outputs that allow use as an inverting/non-inverting translator or as a differential line driver. When the common strobe input is at the low-logic level, it forces all true outputs to a MECL low-logic state and all inverting outputs to a MECL high-logic state.

An advantage of this device is that TTL-level information can be transmitted differentially, via balanced twisted pair lines, to MECL equipment, where the signal can be received by the MC10H115 or MC10H116 differential line receivers. The power supply requirements are ground, +5.0 V, and -5.2 V.

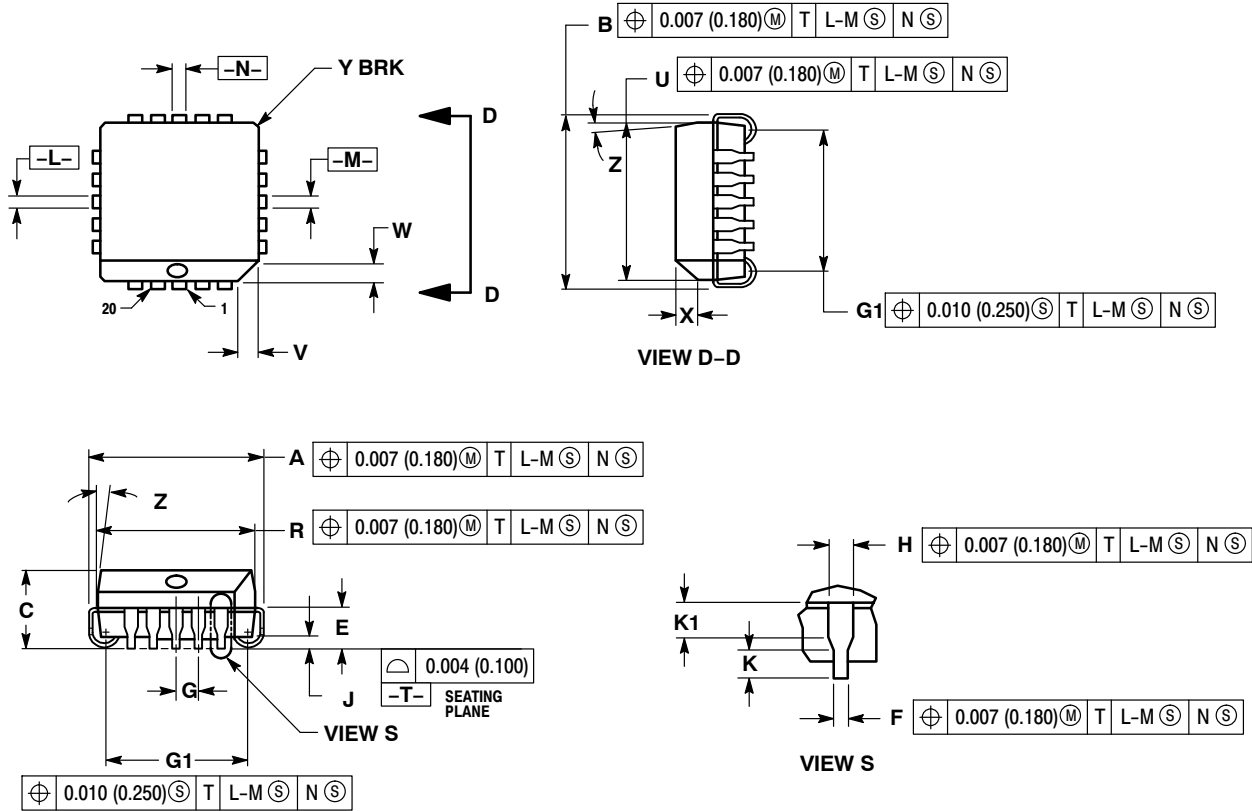
### Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

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## PACKAGE DIMENSIONS

20 LEAD PLLC  
CASE 775-02  
ISSUE F



### NOTES:

1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
2. DIMENSIONS IN INCHES.
3. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	----	0.51	----
K	0.025	----	0.64	----
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	----	0.020	----	0.50
Z	2°	10°	2°	10°
G1	0.310	0.330	7.88	8.38
K1	0.040	----	1.02	----

